

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	70mΩ@10V	4A

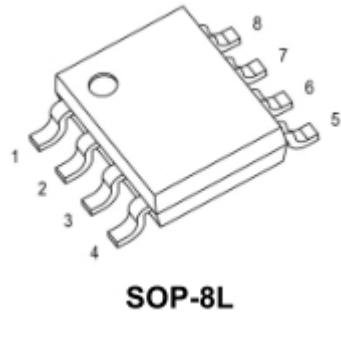
Feature

- N-Channel
- Enhancement mode
- Very low on-resistance @ $V_{GS}=4.5$ V
- Fast Switching

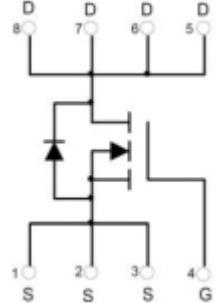
Application

- Synchronous Rectifier
- Primary Switch For Bridge Topology

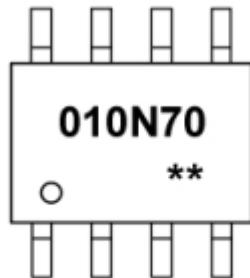
Package



Circuit diagram



Marking



010N70 : Product code

****** : Week code.

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current , $V_{GS} @ 10V^1$	I_D	4	A
Pulsed Drain Current ²	I_{DM}	16	A
Total Power Dissipation	P_D	1.5	W
Thermal Resistance Junction- ambient ¹	$R_{\theta JA}$	85	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction- Case ¹	$R_{\theta JC}$	25	$^\circ\text{C}/\text{W}$
Storage Temperature Range	T_{STG}	-55~ +150	$^\circ\text{C}$
Operating Junction and Storage Temperature Range	T_J	-55~ +150	$^\circ\text{C}$



ZL MOSFET

ZL010N70

Electrical characteristics

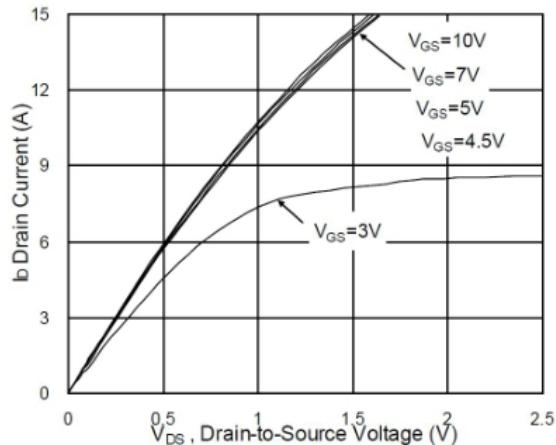
(T_A=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250μA	100			V
Drain-Source Leakage Current	I _{DSS}	V _{DS} = 80V, V _{GS} = 0V, T _J = 25°C			1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	uA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.2	1.8	2.5	V
Static Drain-Source on-Resistance ²	R _{DS(on)}	V _{GS} = 10V, I _D = 2A		70	100	mΩ
		V _{GS} = 4.5V, I _D = 1A		85	110	
Dynamic characteristics						
Total Gate Charge	Q _g	V _{DS} = 80V, V _{GS} = 10V, I _D = 2A		26.2	36.7	nC
Gate-Source Charge	Q _{gs}			3.8	5.32	
Gate-Drain Charge	Q _{gd}			4.8	6.7	
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		1535	2149	pF
Output Capacitance	C _{oss}			60	84	
Reverse Transfer Capacitance	C _{rss}			37	52	
Switching Characteristics						
Turn-On Delay Time	T _{d(on)}	V _{DD} = 50V, V _{GS} = 10V, R _G = 3.3Ω, I _D = 2A		4.2	8.4	nS
Rise Time	T _r			7.6	14	
Turn-Off Delay Time	T _{d(off)}			41	82	
Fall Time	T _f			14	28	
Drain-Source Diode Characteristics						
Continuous Source Current ^{1,4}	I _S	V _G = V _D = 0V, Force Current			2.5	A
Pulsed Source Current ^{2,4}	I _{SM}				10	A
Diode forward voltage ²	V _{SD}	V _{GS} = 0V, I _S = 1A, T _J = 25°C			1.2	V
Reverse Recovery Time	t _{rr}	I _F = 2A, d _I /d _t = 100A/μs, T _J = 25°C		35		nS
Reverse Recovery Charge	Q _{rr}			17		nC

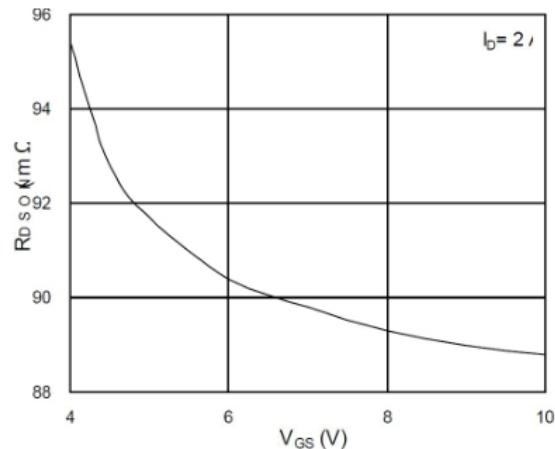
Notes:

- The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

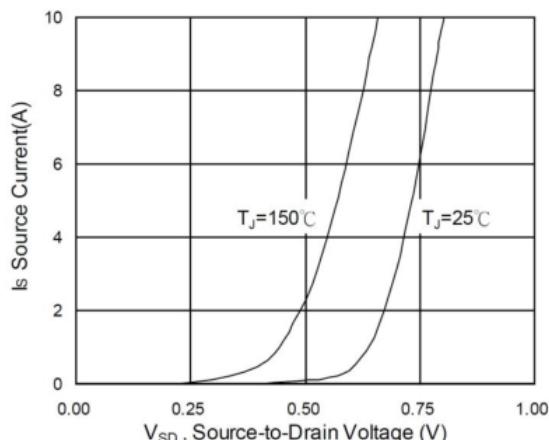
Typical Characteristics



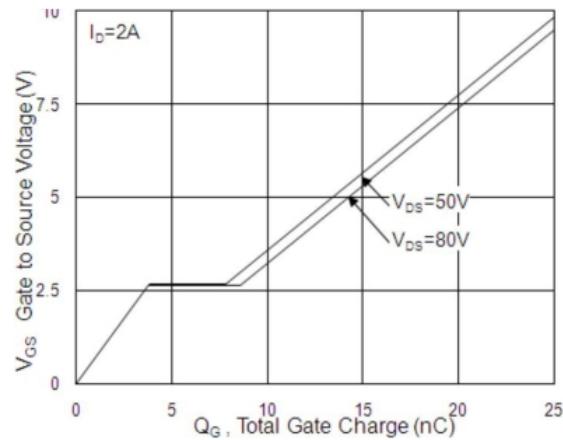
Typical Output Characteristics



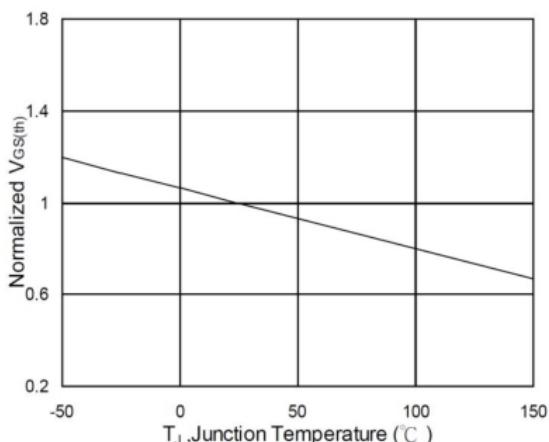
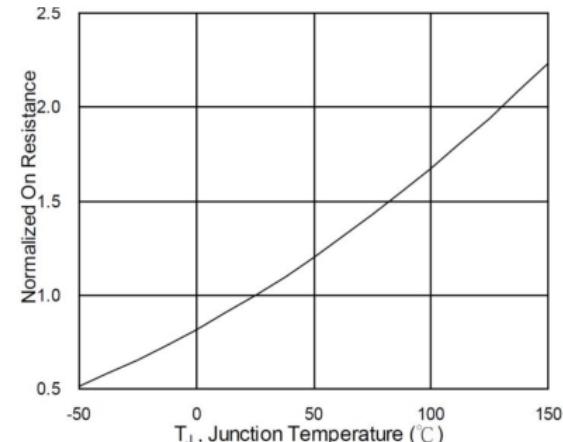
On-Resistance vs. Gate-Source



Forward Characteristics Of Reverse



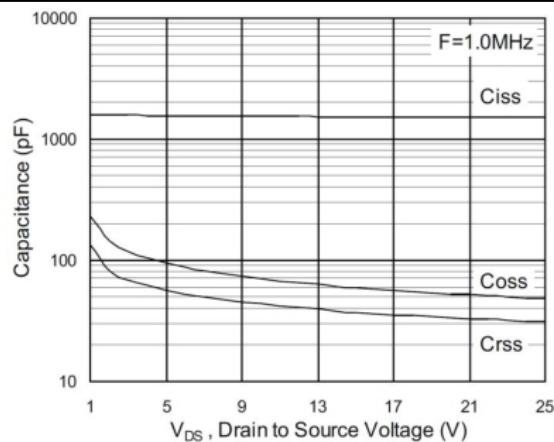
Gate-Charge Characteristics

Normalized $V_{GS(th)}$ vs. T_J Normalized R_{DSON} vs. T_J

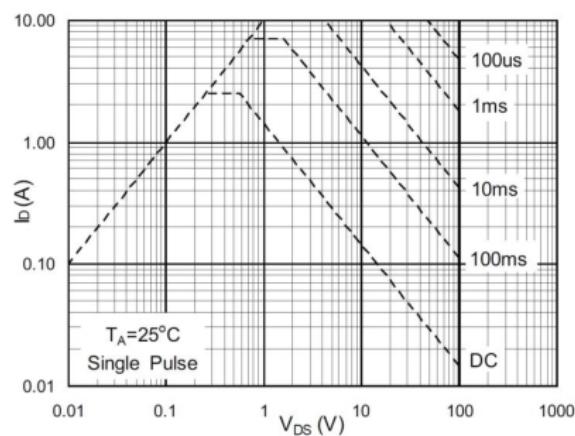


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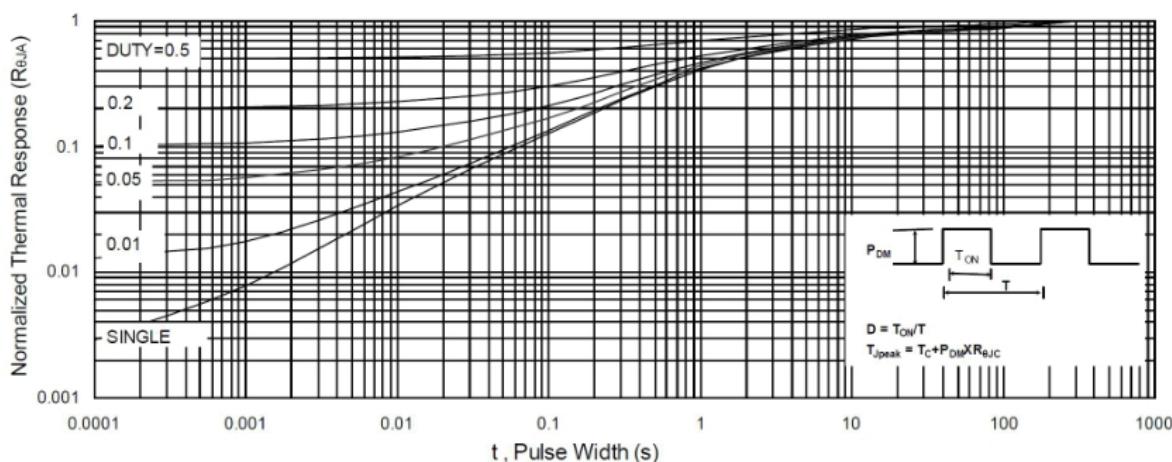
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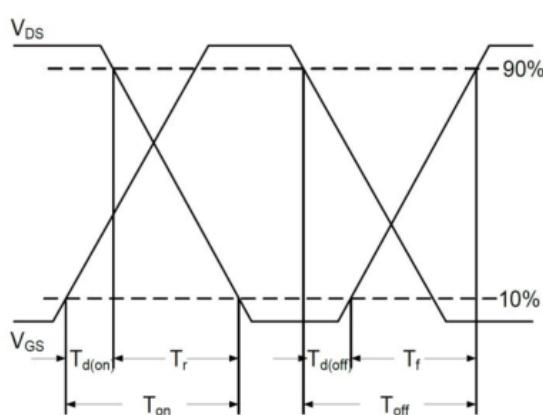
Capacitance



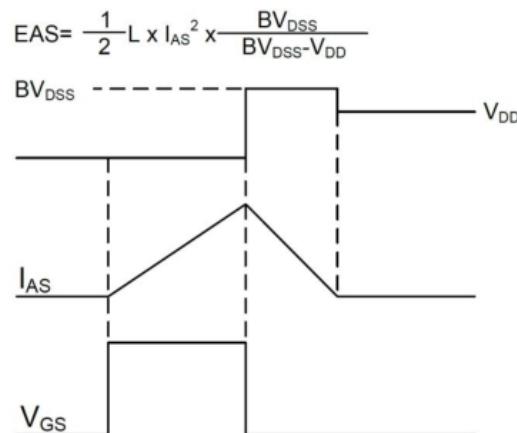
Safe Operating Area



Normalized Maximum Transient Thermal Impedance

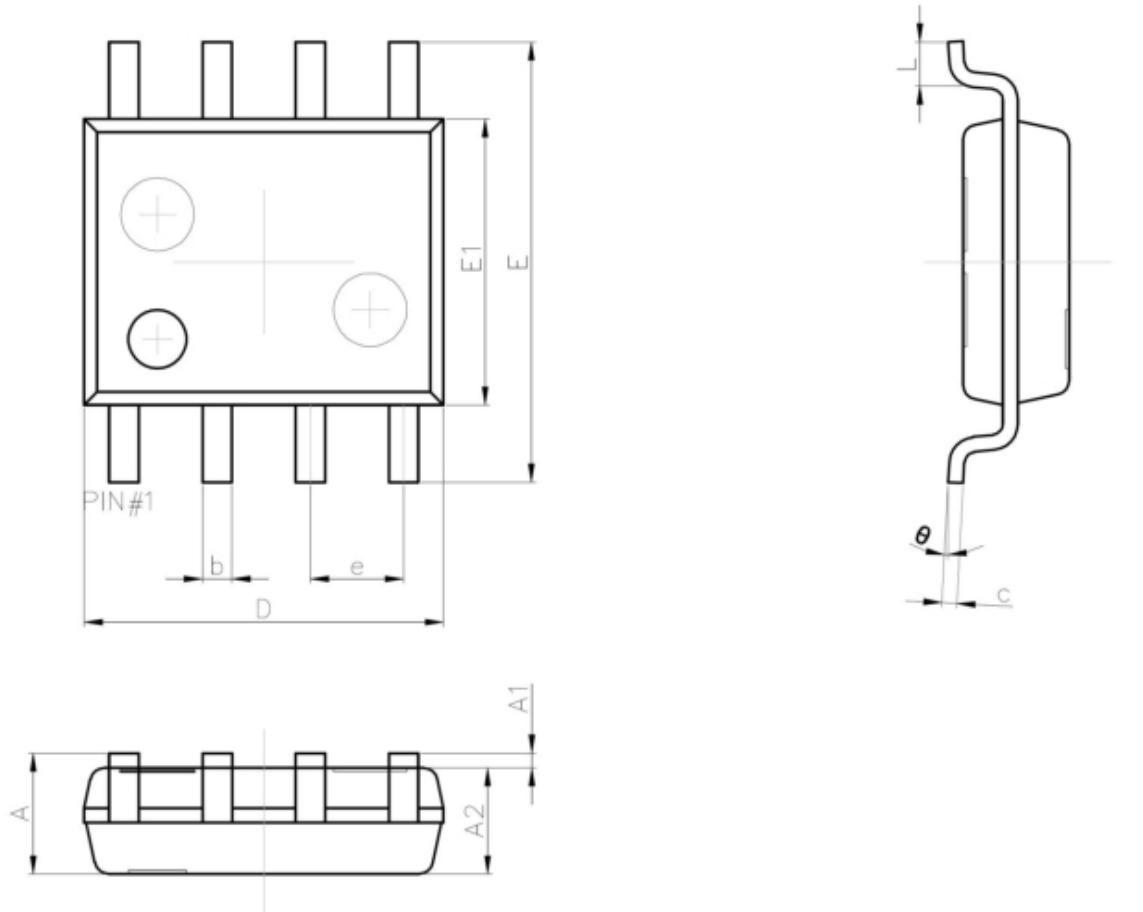


Switching Time Waveform



Unclamped Inductive Switching Waveform

SOP-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
θ	0°	8°